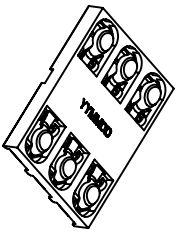


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	R.YUAN	11/13/07

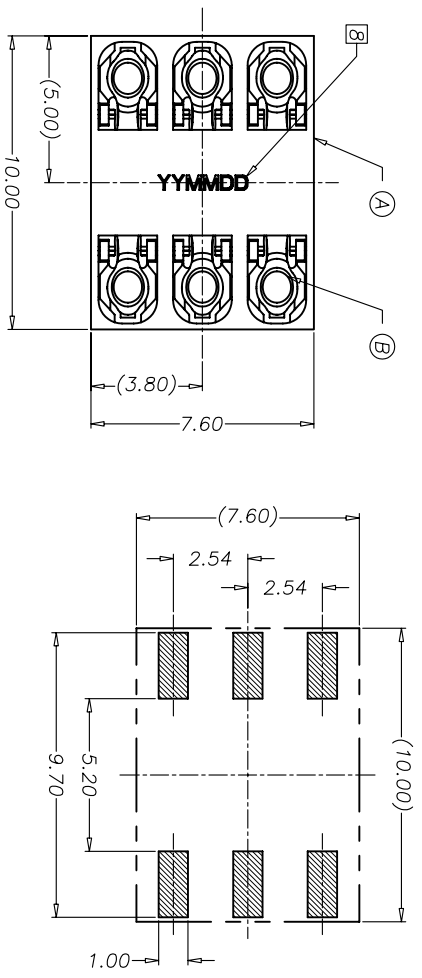


NOTES:
 1. MATERIAL:
 HOUSING: HIGE TEMP. THERMOPLASTIC, U94V-0, COLOR BLACK.
 CONTACT: COPPER ALLOY, T=0.15mm.
 2. FINISH:
 CONTACT: 8u" MIN GOLD PLATING ON CONTACT AREA;
 1u" MIN GOLD PLATING ON SOLDER TAILS;
 50u" ~ 180u" NICKEL UNDERPLATING OVERALL.

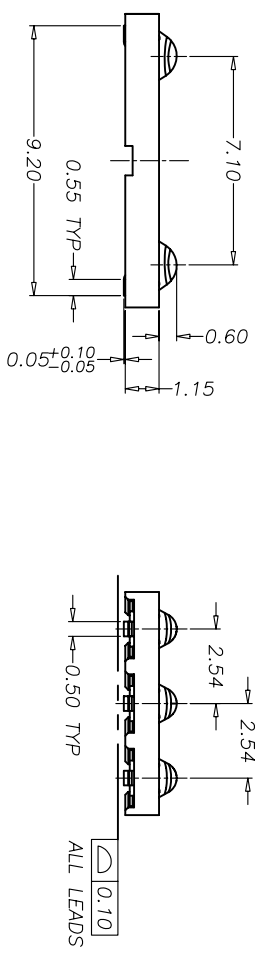
3. SPECIFICATION: SEE "1.2H SIM CARD PRODUCT SPEC."
 4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
 5. TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE".
 6. GREEN PRODUCT IDENTIFICATION IN PACKING: G.P. PASS
 7. FOR REFLOW SOLDERING LEED FREE PROCESS.
 8. DATE CODE DESCRIPTION:
 YYMMDD

9. P/N DESCRIPTION:
 2SM2003-000811

PACKAGE: TAPE AND REEL
 HOUSING COLOR: BLACK
 TERMINAL FINISH: 08u" MIN GOLD



RECOMMENDED PCB LAYOUT
 (COMPONENT SIDE) (TOL. ±0.05)



B	CONTACT	6	SEE NOTES	SEE NOTES
A	HOUSING	1	SEE NOTES	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS:		ANGLES:		
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1'	
X.XX	:±0.2			
TITLE SIM CARD 1.2H				
DWN	REV'D	PART NO.	2SM2003-000811	
CHKD	ZK CHEN	SCALE:	1/1	
APVD	SEAN	SIZE:	A3	
		SHEET:	1 OF 1 REV. A	
CUSOTMWER COPY				

Singatron Electronic(Chung-Shan) Co., Ltd.
 信譽電子(中山)有限公司